

P17856.A03

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Please add claims 22-43 as follows:

b 3 sub ca' 22. A printed circuit board according to claim 2, wherein the roughened layer is formed on at least a part of the surface inclusive of a side surface of the conductor circuit.

~~23. A printed circuit board according to claim 2, wherein the roughened layer is formed on at least a part of a side face of the conductor circuit.~~

24. A printed circuit board according to claim 2, wherein the roughened layer is a plated layer of copper-nickel-phosphorus alloy.

25. A printed circuit board according to claim 3, wherein the roughened layer is a plated layer of copper-nickel-phosphorus alloy.

26. A printed circuit board according to claim 4, wherein the roughened layer is a plated layer of copper-nickel-phosphorus alloy.

27. A method of producing a printed circuit board according to claim 7, wherein the roughened layer is formed by plating of copper-nickel-phosphorus alloy.

28. A printed circuit board according to claim 14, wherein the alignment mark is an opening portion formed by exposing only the surface of the conductor layer from a solder resist formed on the conductor layer.

Sub C 98 29. A printed circuit board according to claim 14, wherein the alignment mark is used for positioning to a printed mask.

~~30. A printed circuit board according to claim 15, wherein the alignment mark is used for positioning to a printed mask.~~

b3 Sub Cnt 7 31. A printed circuit board according to claim 16, wherein the alignment mark is used for positioning to a printed mask.

32. A printed circuit board according to claim 17, wherein the alignment mark is used for positioning to a printed mask.

33. A printed circuit board according to claim 18, wherein the alignment mark is used for positioning to a printed mask.

34. A printed circuit board according to claim 14, wherein the alignment mark is used for an IC chip mounting.

35. A printed circuit board according to claim 15, wherein the alignment mark is used for an IC chip mounting.

36. A printed circuit board according to claim 16, wherein the alignment mark is used for an IC chip mounting.

37. A printed circuit board according to claim 17, wherein the alignment mark is used for an IC chip mounting.

38. A printed circuit board according to claim 18, wherein the alignment mark is used for an IC chip mounting.

39. A printed circuit board according to claim 14, wherein the alignment mark is used for positioning during mounting of a printed circuit board packaged as a semiconductor element to another printed circuit board.